

US00D964443S

(12) **United States Design Patent** (10) **Patent No.:** **US D964,443 S**
Murata (45) **Date of Patent:** **** Sep. 20, 2022**

(54) **GAS INLET ATTACHMENT FOR WAFER PROCESSING APPARATUS**

H01L 21/02263; H01L 21/31; H01L 21/205; H01L 21/0228; H01L 21/02164
See application file for complete search history.

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(73) Assignee: **KOKUSAI ELECTRIC CORPORATION**, Tokyo (JP)

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(**) Term: **15 Years**

(21) Appl. No.: **29/770,855**

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(Continued)

(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **15-09**

Primary Examiner — Patricia A Palasik

(52) **U.S. Cl.**
USPC **D15/144.1**

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(58) **Field of Classification Search**
USPC D13/122, 182, 184, 199; D15/144, D15/144.1, 144.2; D8/2, 382
CPC . C23C 16/00; C23C 16/455; C23C 16/45502; C23C 16/45504; C23C 16/45506; C23C 16/45508; C23C 16/4551; C23C 16/45512; C23C 16/45514; C23C 16/45517; C23C 16/45563; C23C 16/4557; C23C 16/45576; C23C 16/45578; C23C 16/402; C23C 16/4584; C23C 16/45587; C23C 16/45525; C23C 16/45544; C23C 16/46; C23C 16/45527; C23C 16/4412; H01L 21/00; H01L 21/02;

(57) **CLAIM**

The ornamental design for a gas inlet attachment for wafer processing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a gas inlet attachment for wafer processing apparatus showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is a rear elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof; and,

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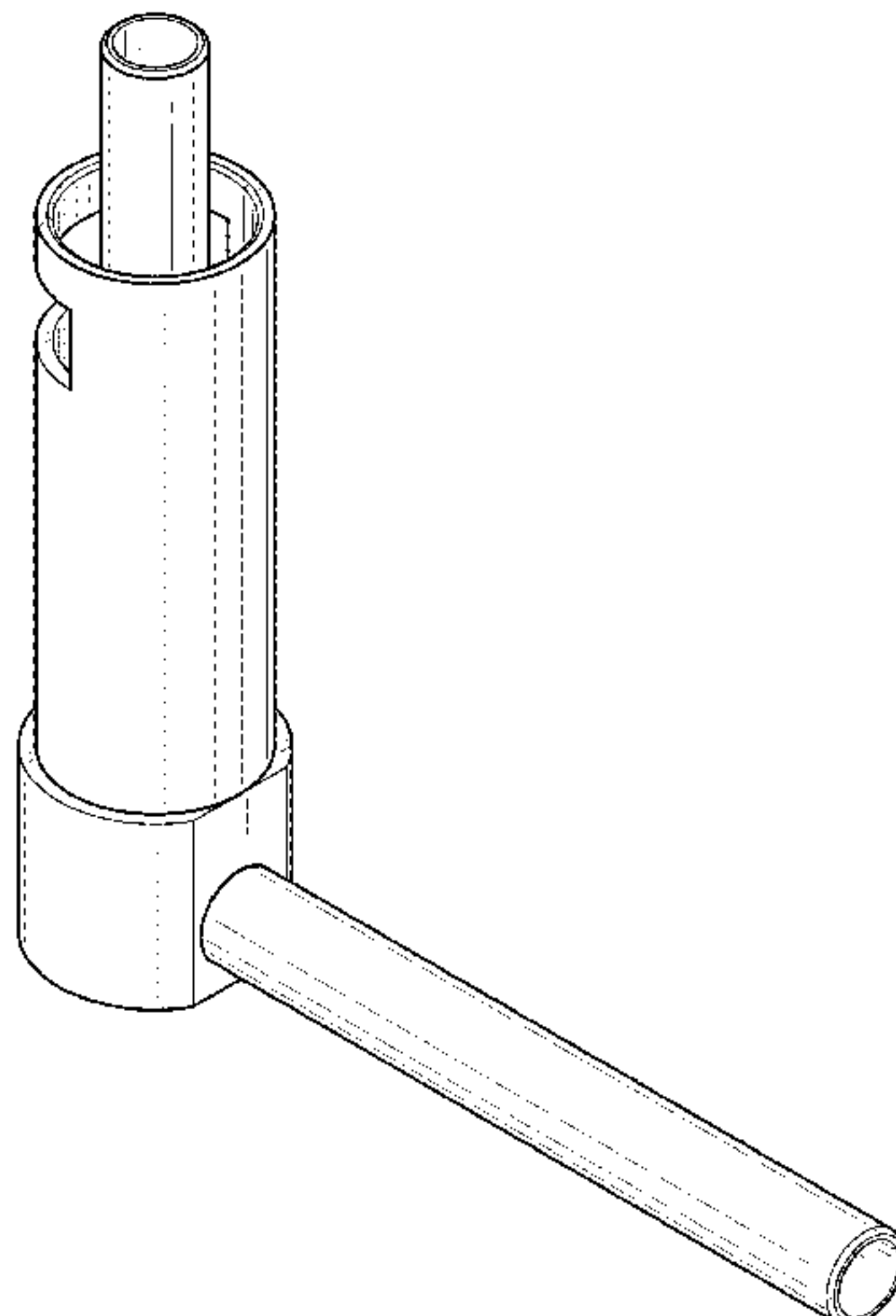


FIG. 8 is a cross sectional view taken along line 8-8 in FIG. 4.

1 Claim, 6 Drawing Sheets

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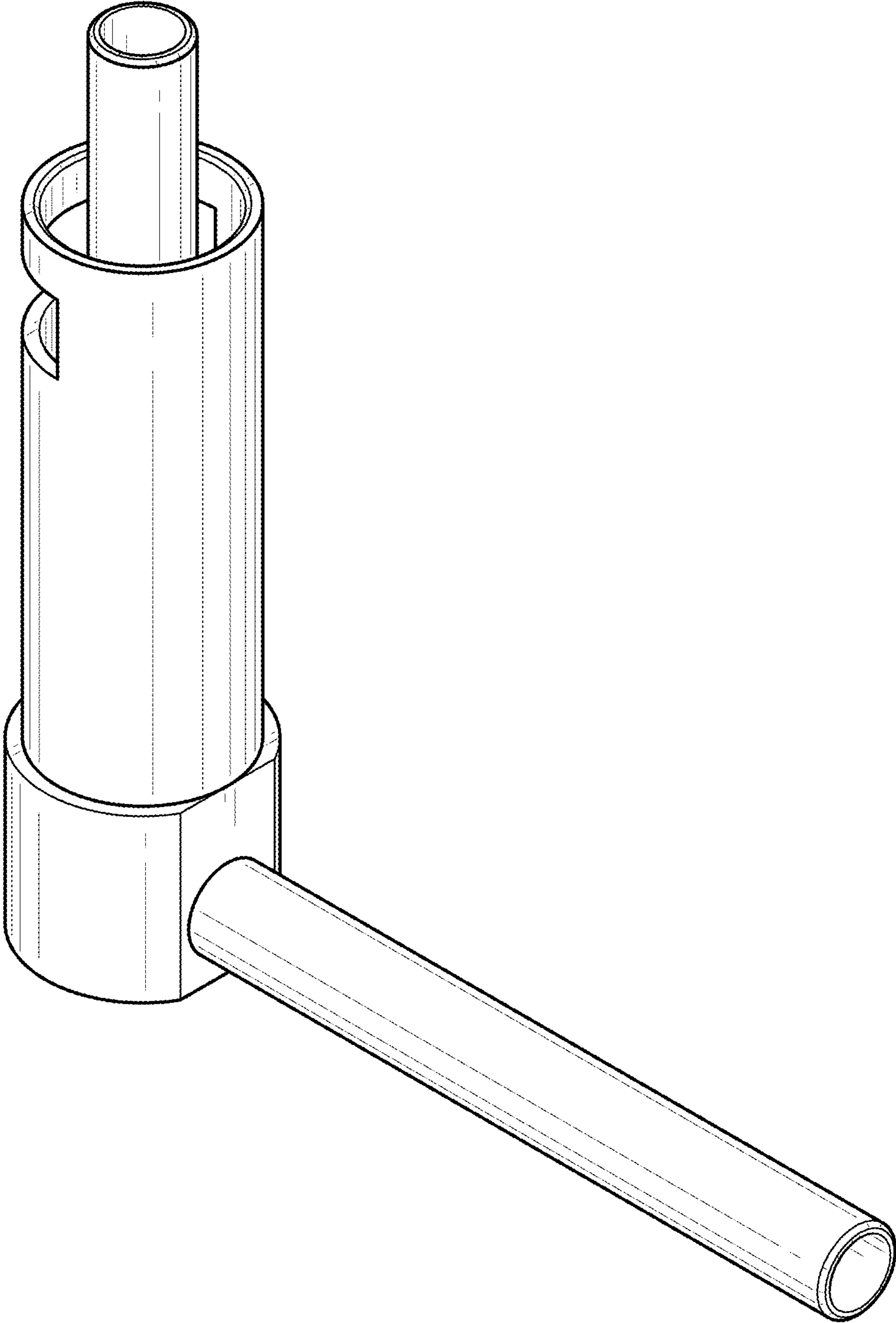


FIG. 1

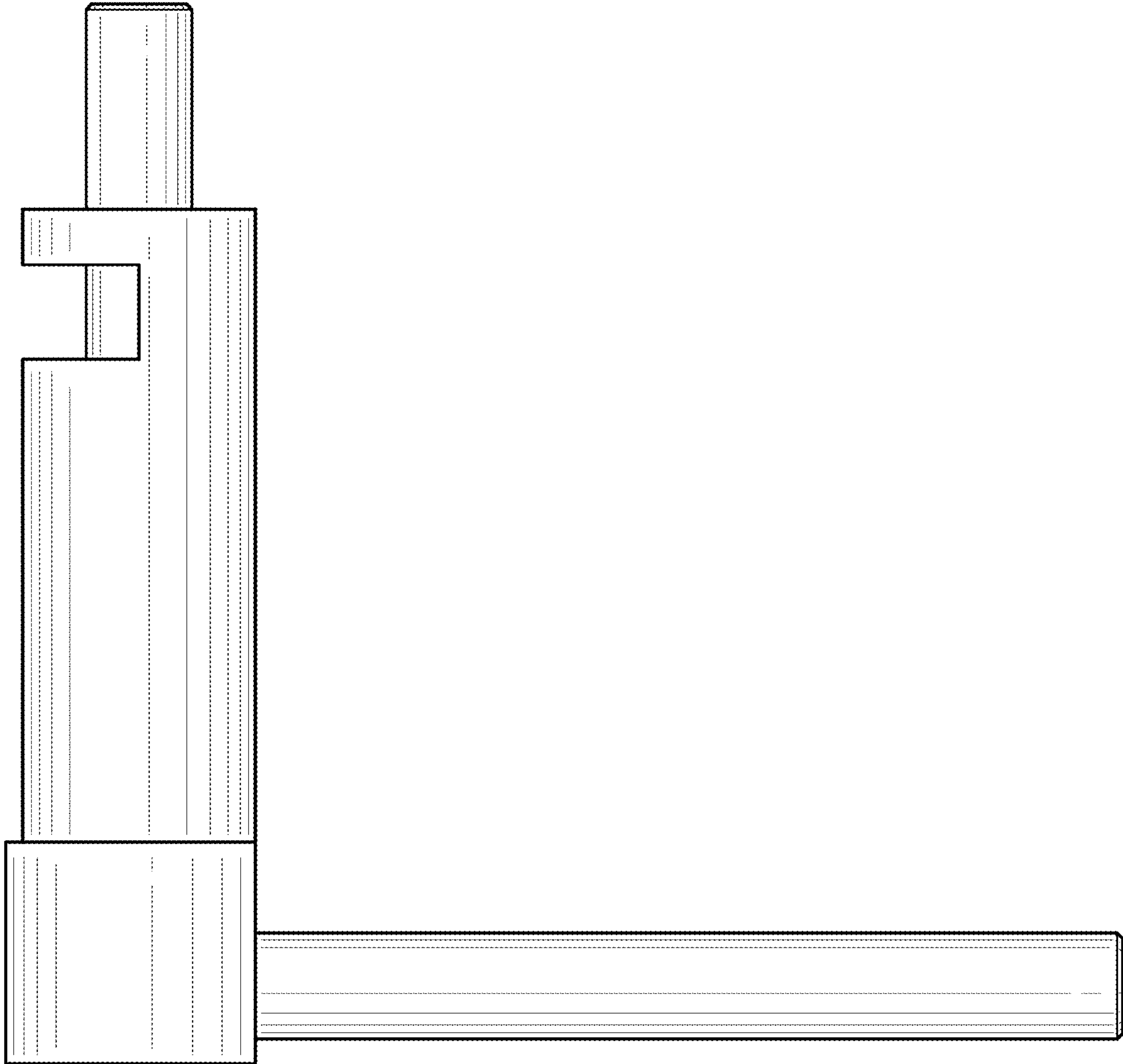


FIG. 2

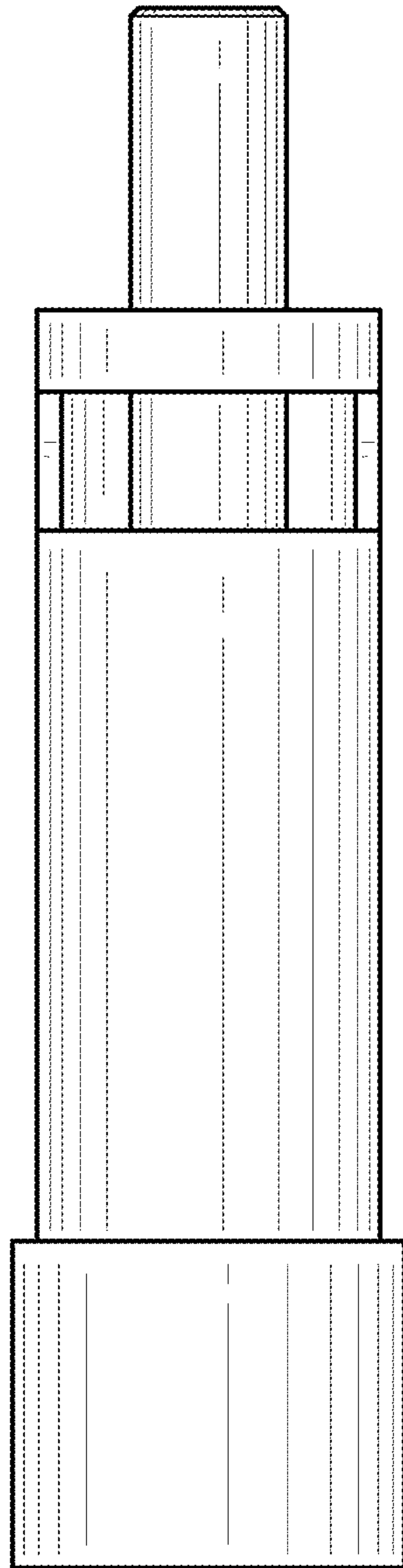


FIG. 3

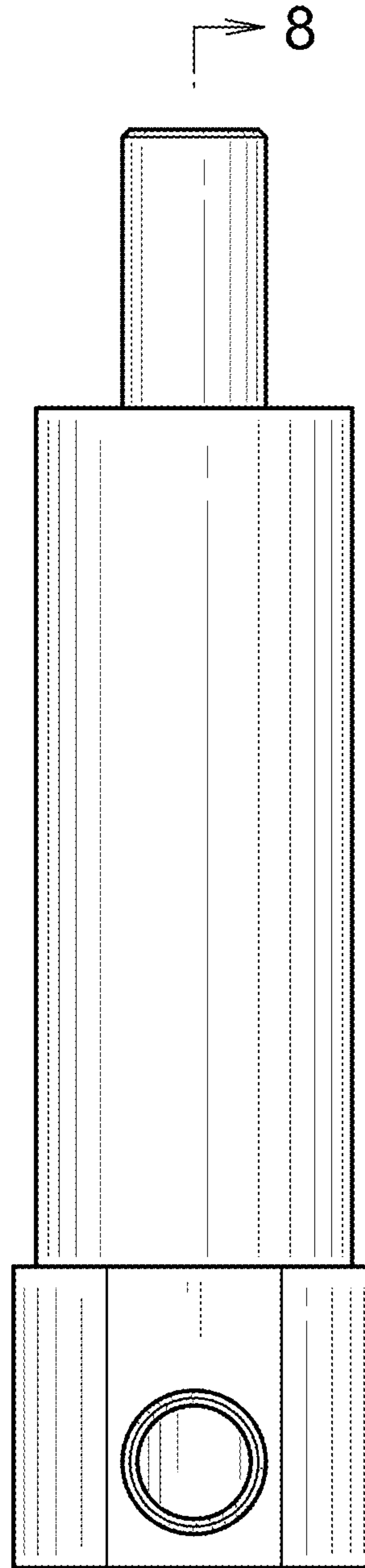


FIG. 4

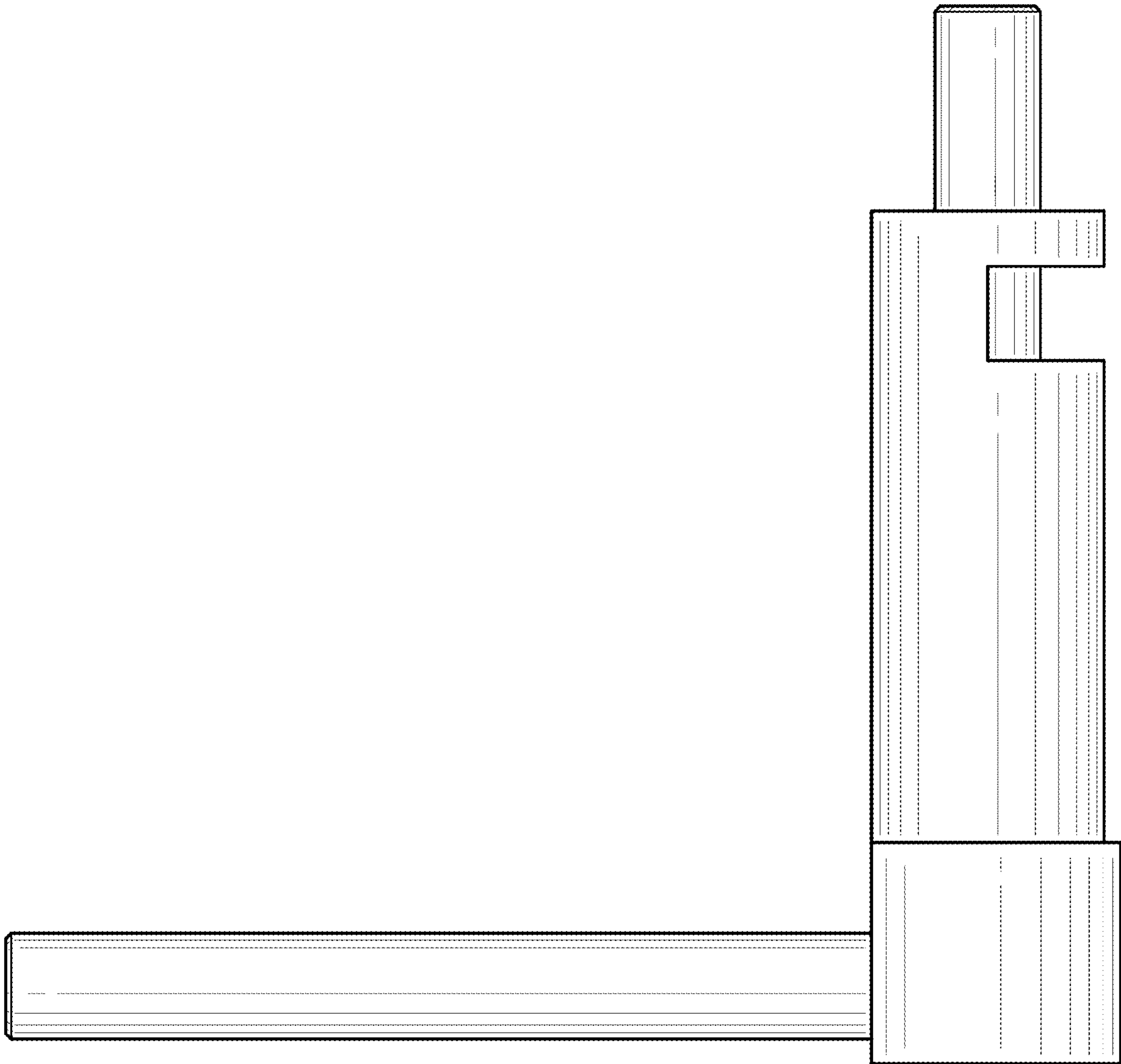


FIG. 5

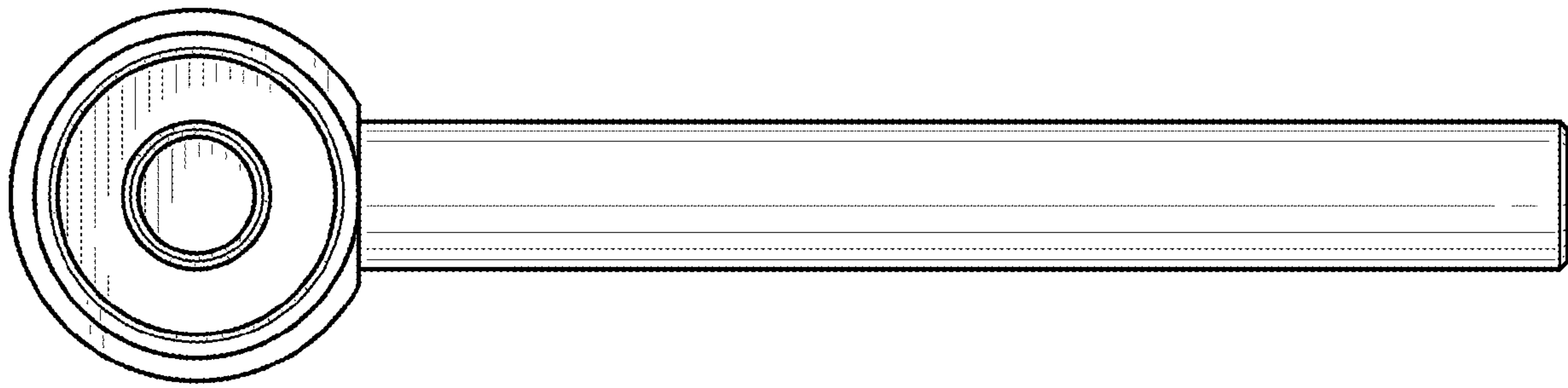


FIG. 6

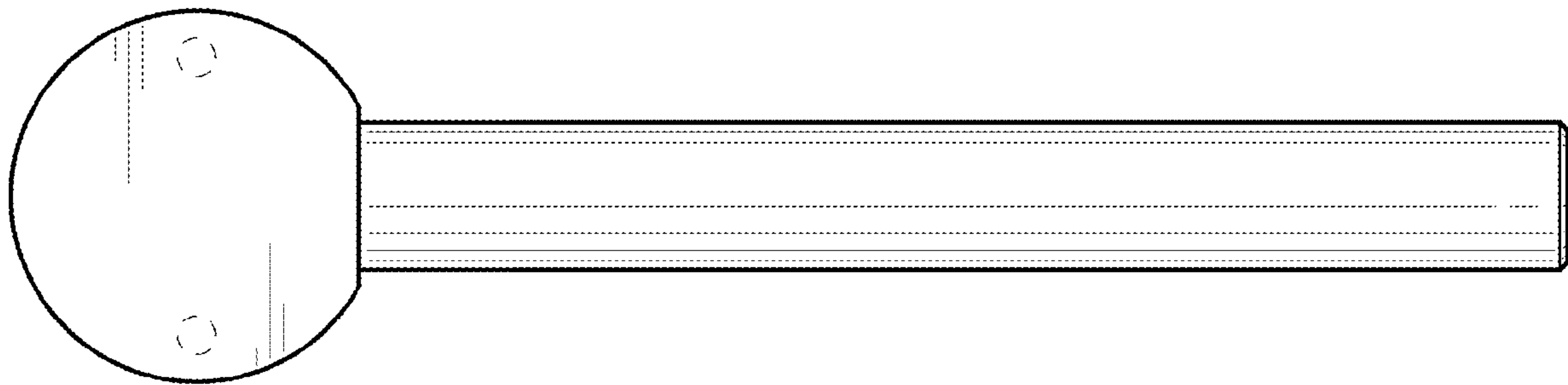


FIG. 7

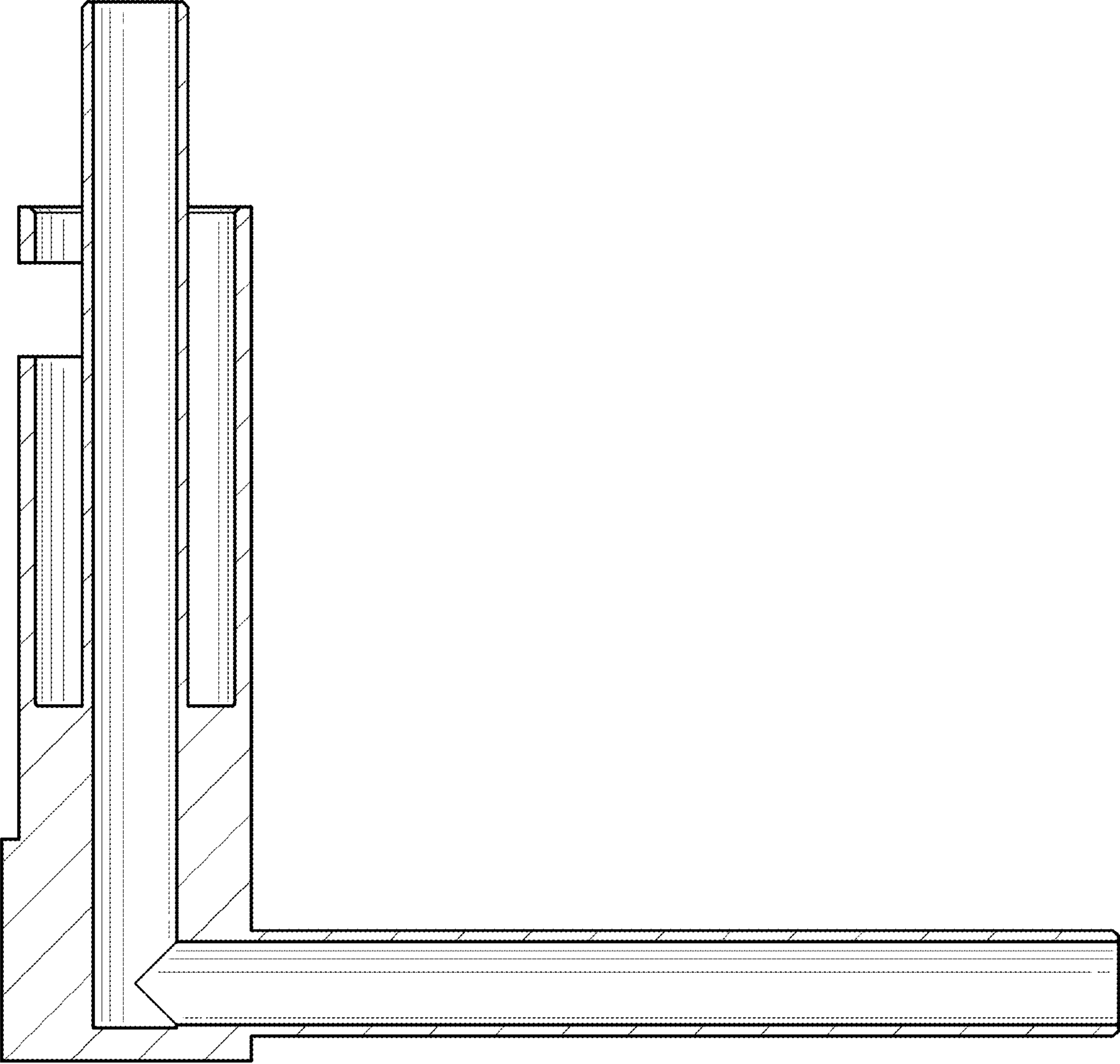


FIG. 8